



Material Content Data Sheet



Sales Product Name		TLE8457BLE		Issued		10. August 2018		
MA#		MA001579606						
Package		PG-TSON-8-1		Weight*		26.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	4.53	4.53	45325	45325
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		438	
	non noble metal	iron	7439-89-6	0.236	0.88		8763	
wire	non noble metal	copper	7440-50-8	9.586	35.58	36.51	355825	365136
	non noble metal	copper	7440-50-8	0.040	0.15	0.15	1477	1477
	organic material	carbon black	1333-86-4	0.030	0.11		1109	
encapsulation	plastics	epoxy resin	-	1.539	5.71		57128	
	inorganic material	silicondioxide	60676-86-0	13.373	49.65	55.47	496403	554640
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14187	14187
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1614	1614
glue	plastics	epoxy resin	-	0.119	0.44		4405	
	noble metal	silver	7440-22-4	0.356	1.32	1.76	13216	17621
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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